

Dual N-Channel 100V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^a		
100	0.018at V _{GS} = 10 V	35		
	0.022at V _{GS} = 4.5 V	36		

FEATURES

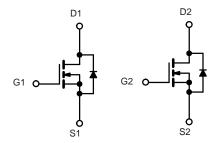
- 175 °C Junction Temperature
- Trench technology Power MOSFET
- Material categorization:







Top View



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Gate-Source Voltage	V_{GS}	±20	V				
Continuous Drain Current (T,I = 175 °C) ^b	T _C = 25 °C	I_	35				
Continuous Drain Current (1 _J = 175 °C) ²	T _C = 100 °C	- I _D	20 ^a				
Pulsed Drain Current	I _{DM}	105	А				
Continuous Source Current (Diode Conduction)	I _S	76 ^a					
Avalanche Current	I _{AS}	82					
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	110	mJ			
Maximum Power Dissipation	T _C = 25 °C	P _D	136	W			
Maximum Fower Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}	VV			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Marian and Lucation to Ambienta	t ≤ 10 sec	Р	15	18			
Maximum Junction-to-Ambient ^a	Steady State	R_{thJA}	60	50	°C/W		
Maximum Junction-to-Case		R _{thJC}	0.85	1.1			

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		$V_{DS} = 30V, V_{GS} = 0 V, T_{J} = 175 °C$			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	60			Α	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.018		Ω	
Desir Occurs Oc Otata Basistanah	P	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008			
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010			
		V _{GS} = 4.5 V, I _D = 12A		0.022			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S	
Dynamic							
Input Capacitance	C _{iss}			3900		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}$		470			
Reverse Transfer Capacitance	C _{rss}			225			
Total Gate Charge ^c	Q_g			89	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		26		nC	
Gate-Drain Charge ^c	Q_{gd}			23			
Turn-On Delay Time ^c	t _{d(on)}			21	25		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 0.6 \Omega$		15	25	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50		
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)					
Pulsed Current	I _{SM}				105	Α	
Diode Forward Voltage	V_{SD}	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns	

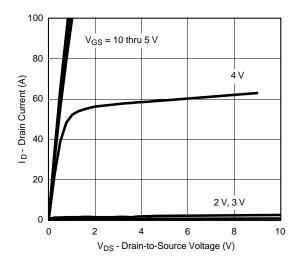
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

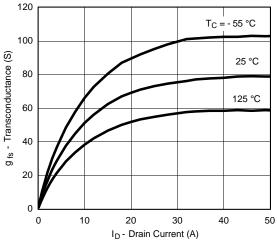
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



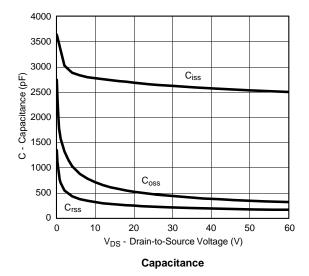
TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



Transconductance

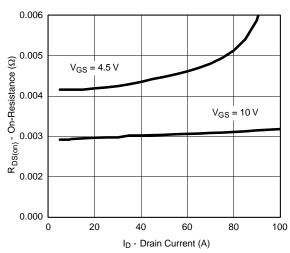


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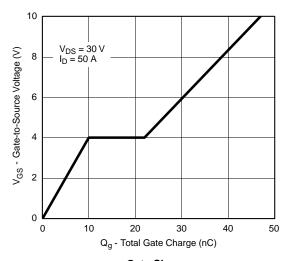
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Transfer Characteristics



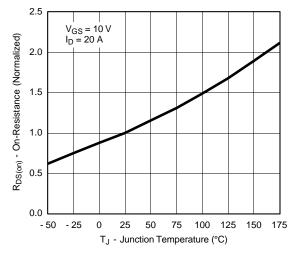
On-Resistance vs. Drain Current



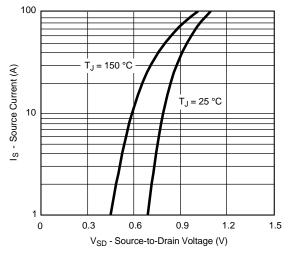
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature

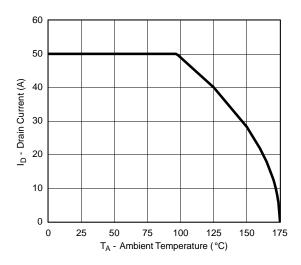


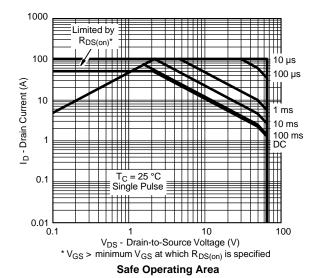
Source-Drain Diode Forward Voltage



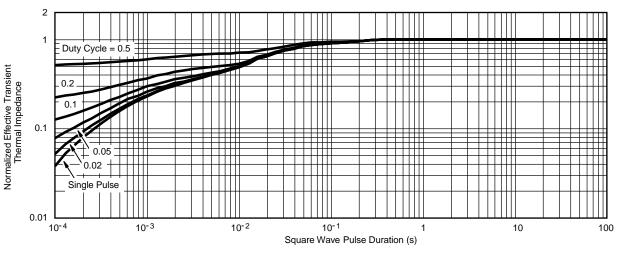
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THERMAL RATINGS





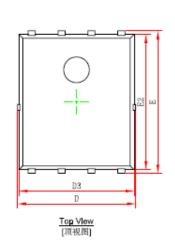
Maximum Drain Current vs. Ambient Temperature

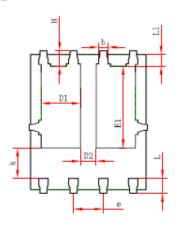


Normalized Thermal Transient Impedance, Junction-to-Case

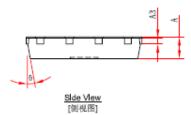


PDFNWB5×6-8L-A PACKAGE OUTLINE DIMENSIONS





Bottom View [背视图]



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	0.254 REF.		REF.	
D	4.944	5.096	0.195	0.201	
Е	5.974	6.126	0.235	0.241	
D1	1.470	1.870	0.058	0.074	
D2	0.470	0.870	0.019	0.034	
E1	3.375	3.575	0.133	0.141	
D3	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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